ABSTRACT

The present invention is a semiconductor device which can improve the adhesive force between a semiconductor chip and a substrate. This semiconductor device 60 has a semiconductor chip 18, a die pad (metallic portion) 16 on which the semiconductor chip 18 is fixedly mounted and supported through an adhesive layer 62, and a sealing resin 24 for sealing the die pad 16 and semiconductor chip 18. The adhesive layer 62 includes a plurality of conductive adhesive regions 66 and a plurality of insulative adhesive regions 64 together.